

July 3, 2003

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile     Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

**Divisional Patent Application of**  
Serial No.: 09/950,227 9/10/01

YANG-TUNG FAN, CHENG-YU CHU, FU-JIER FAN,  
SHIH-JANE LIN, CHIOU-SHIAN PENG, YEN-MING  
CHEN, KUO-WEI LIN

NEW BUMP PROCESS TO INCREASE BUMP HEIGHT  
AND TO CREATE A MORE ROBUST BUMP  
STRUCTURE

**PRELIMINARY AMENDMENT**

Dear Sir:


This is a preliminary amendment for the above referenced Divisional Patent  
Application. Please amend the above identified application for patent as follows:

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States  
Postal Service as first class mail in an envelope addressed to: Commissioner of Patents  
and Trademarks, Washington, D.C. 20231, on July 3, 2003.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date

 7/3/03